

Computer Electronics

Lecture 22: SRAM

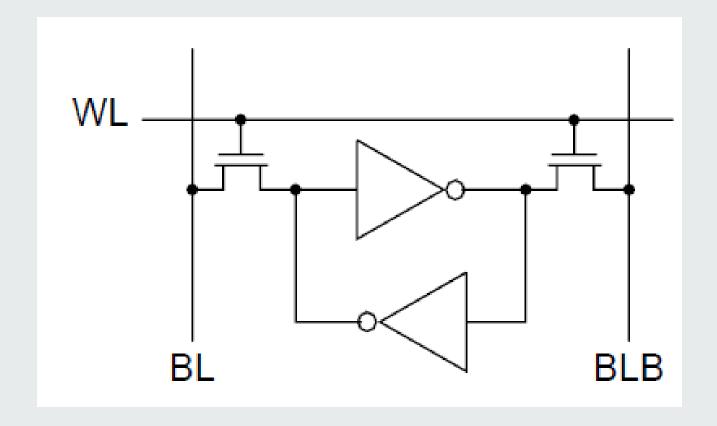


Outline

- Static memory cells
- DRAM vs. SRAM
- SRAM read operation
- SRAM write operation
- SRAM sense and write amplifiers

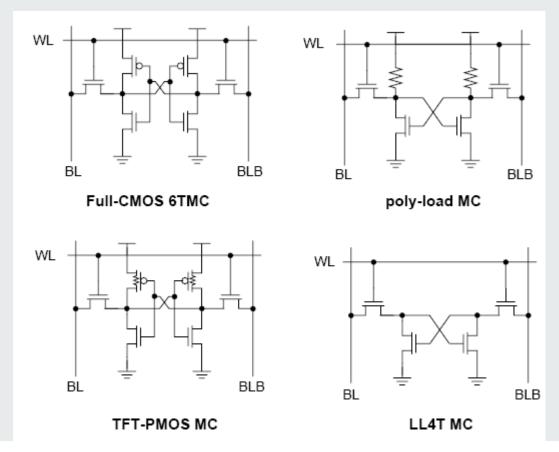


A static memory cell





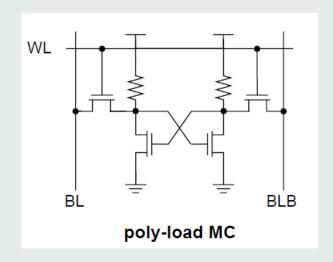
Static cell types





Poly load

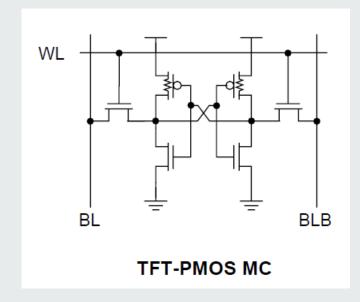
- Implemented in a separate polysilicon layer
- Advantage:
 - 30% area reduction
- Disadvantages
 - Non standard technology
 - Resistors can't be shrunk anymore





TFT PMOS

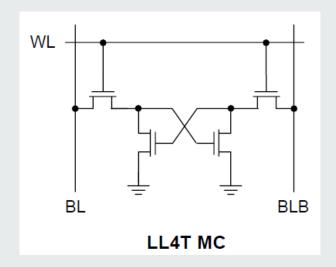
- Polysilicon transistor built on top of NMOS transistor
- Advantage:
 - Area reduction
- Disadvantage
 - Non standard technology





Loadless SRAM Cell

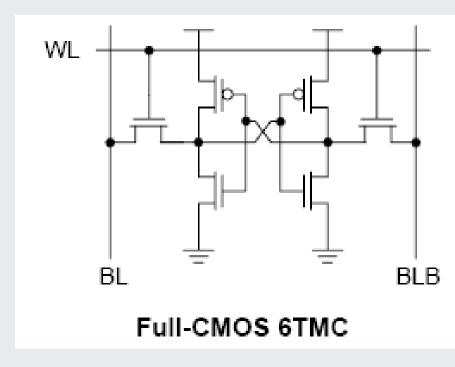
- Information stored in gate capacitor
- Advantages:
 - Standard technology
 - Up to 65% area reduction!
- Disadvantage
 - Leakage current may wipe info away





6T standard SRAM cell

- Most common SRAM cell
- Advantage:
 - Implemented with regular CMOS technology
- Disadvantage
 - Larger area



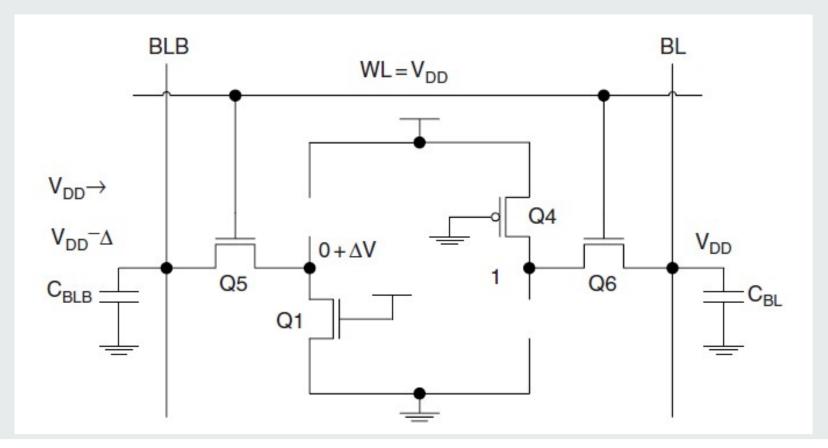


SRAM vs DRAM

- Cells are much larger: 6T instead of 1T+1C(parasitic). DRAM is <u>denser</u>
- Cells consume only leakage current, no expensive periodic refresh. SRAM is lower power
- Cost is exponential with area due to Yield problems
- SRAM much more expensive than DRAM (cost per bit)



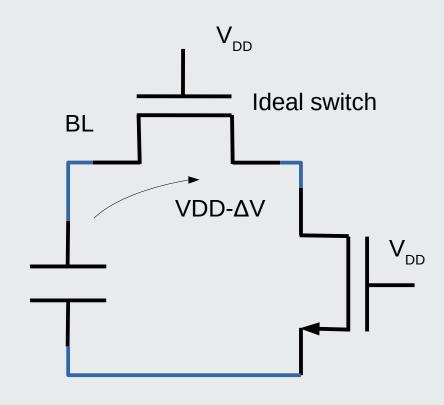
SRAM read operation





SRAM read circuit

- Pre-charge BL at VDD
- Turn on the access switch
- Wait for a voltage at BL to drop
- Note that BLB voltage stuck at V_{DD}
- $I_D = k(V_{DD}-V_T)^2$ (constant current discharge)
- $\Delta t = C_d \Delta V / I_D$



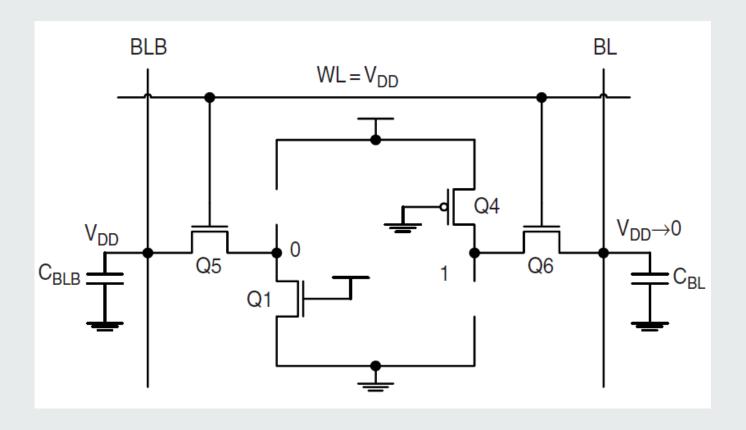


SRAM read procedure

- 1. Pre-charge BL and BLB at the same voltage VDD
- 2. Turn on the access transistors (row decoder)
- 3. Wait for a voltage difference to develop between BL and BLB
- 4. Select the column (column decoder) to access the (shared) sense amplifier and wait for voltage levels to be restored
- 5. Read the SRAM data IO pins



SRAM write operation

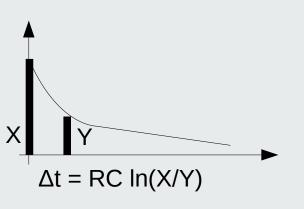


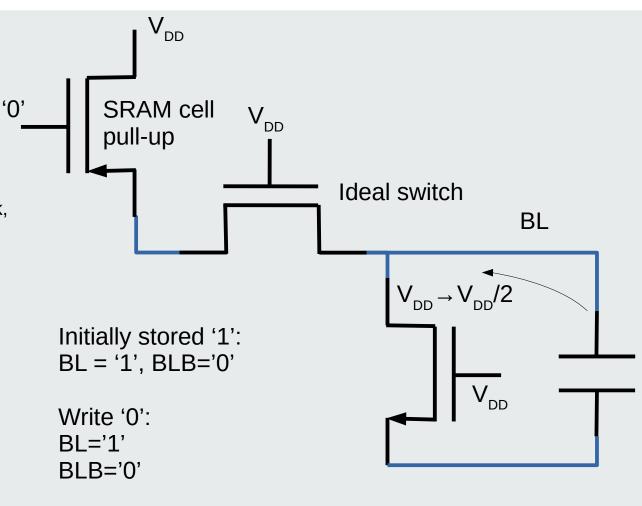


SRAM write circuit

- Pre-charge BLB at VDD
- Turn on the access switch (row)
- Apply write amp (column)
- BL discharges slowly via cell
- BLB discharges fast via write transistor
- Simple model: write transistor is resistor Ra, cell transistor too weak, ideal switch

$$\Delta t = R_{A}C_{D}\ln(\frac{V_{DD}}{V_{DD}/2}) = R_{A}C_{D}\ln(2)$$





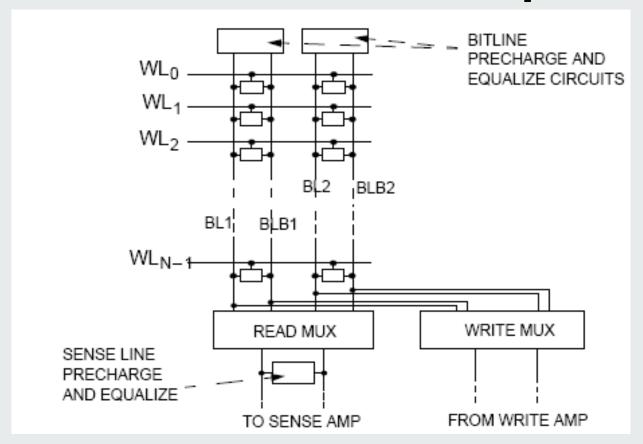


SRAM write procedure

- 1. Pre-charge BL and BLB at VDD
- 2. Apply the write values to the chip IO pins
- 3. Select the row to provide an electrical access to the cell
- 4. Select the column so that the (shared) write amplifier will drive and force the cell to the desired state



Shared sense and write amps





SRAM write amplifier

- Use pre-charge facility already in place for reading
- Use simple pull-down transistors for writing
- If pre-charge value is VDD then only one line needs to be pulled down!

